

Title (en)

METHOD FOR ELECTRICALLY EXAMINING ELECTRONIC COMPONENTS OF AN INTEGRATED CIRCUIT

Title (de)

VERFAHREN ZUR ELEKTRISCHEN UNTERSUCHUNG VON ELEKTRONISCHEN BAUELEMENTEN EINES INTEGRIERTEN SCHALTKREISES

Title (fr)

PROCÉDÉ D'EXAMEN ÉLECTRIQUE DE COMPOSANTS ÉLECTRONIQUES D'UN CIRCUIT INTÉGRÉ

Publication

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Application

EP 19809377 A 20191108

Priority

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Abstract (en)

[origin: WO2020114533A1] The invention relates to a method for electrically examining electronic components of an integrated circuit. According to the invention, a method for electrically examining electronic components of an integrated circuit (1) is provided, comprising a target region (3) to be examined, in which electronic components having contact points (5) are located, and a residual region referred to as non-target region (2), in which an examination is carried out using a combined SEM/AFM nanaprobe. In a first step, the non-target region (2) is at least partially imaged with the scanning electron microscope part of the SEM/AFM nanaprobe, and in a subsequent step, the target region (3) is at least partially imaged with the scanning force microscope part of the SEM/AFM nanaprobe.

IPC 8 full level

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